

General Description

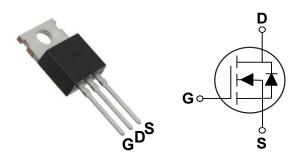
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
250 V	33 mΩ	60 A

Features

- $\cdot R_{DS(ON)} \le 33 m \Omega @V_{GS} = 10V$
- · Improved dv/dt Capability
- · Fast Switching
- · Green Device Available

TO-220 Pin Configuration



Applications

- ·UPS
- BLDC

Symbol	Parameter	Rating	Unit
V_{DS}	Drain-Source Voltage	250	V
V_{GS}	Gate-Source Voltage	±30	V
I _D	Drain Current – Continuous (T _A =25°C)	60	Α
I _{DM}	Drain Current – Pulsed (NOTE 1)	230	Α
EAS	Single Pulse Avalanche Energy (NOTE 2)	300	m
P _D	Power Dissipation (T _C =25°C)	125	W
T_J	Operating Junction Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
larking Code		NT033	

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	60	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	1	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	250			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =250V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V		-	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V_{GS} =10V , I_D =35A			33	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS} , I_D =250uA	3.6		5.0	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			200		
Q_{gs}	Gate-Source Charge	V_{DD} =100V , V_{GS} =10V , I_{D} =35A		28		nC
Q_{gd}	Gate-Drain Charge			60		
$T_{d(on)}$	Turn-On Delay Time			45		
T _r	Rise Time	V_{DS} =50V , R_G =2.5 Ω , I_D =35A ,		70		nS
$T_{d(off)}$	Turn-Off Delay Time	V _{GS} =10V		110		110
T_f	Fall Time			90		
C _{iss}	Input Capacitance			7000		
C _{oss}	Output Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz		480		pF
C _{rss}	Reverse Transfer Capacitance			210		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Body Diode Current				58	Α
I _{SM}	Pulsed Diode Forward Current				230	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =35A		-	1.2	V
t _{rr}	Reverse Recovery Time	V_{GS} =0V , I_S =30A , V_{DD} =50V ,		120		nS
Q_{rr}	Reverse Recovery Charge	dI _F /dt=100A/us		0.55		uC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =50V, I_{AS} =35A, R_{G} =25 Ω , V_{GS} =10V.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- $\label{eq:continuous} \textbf{4. Essentially independent of operating temperature}.$





Characteristics Curves

FIG. 1- I_D vs. T_A

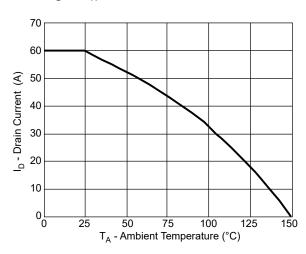


FIG. 2- Normalized BV_{DSS} vs. T_J

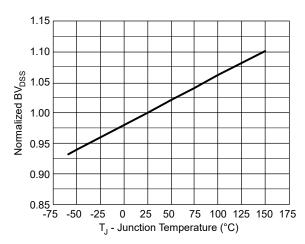


FIG. 3- Normalized $R_{DS(ON)}$ vs. T_J

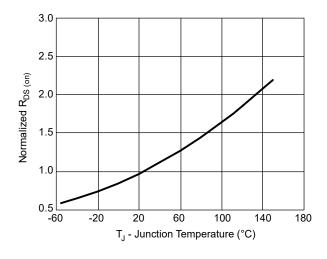


FIG. 4- Gate Charge Characteristics

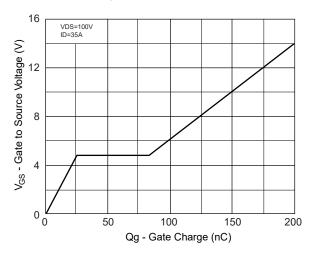


FIG. 5- Drain-Source Diode Forward

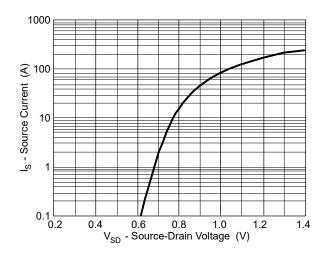
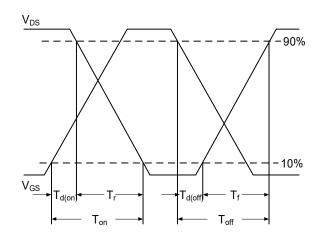


FIG. 6- Switching Time Waveform

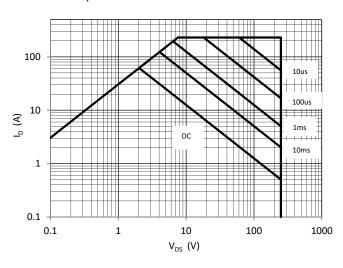




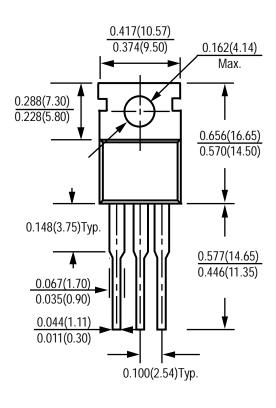


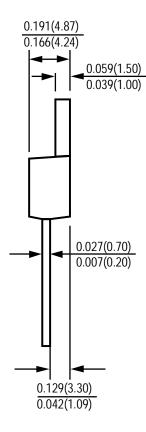
Characteristics Curves

FIG. 7- Safe Operation Area



Package Outline Dimensions





TO-220 Dimensions in inches and (millimeters)





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